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PATENT
Attorney Docket No. ASC-025DV1C1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS:

Cheng, et al.

SERIAL NO.:

10/802,185

GROUP NO.:

2813

FILING DATE:

March 17, 2004

EXAMINER:

Craig Thompson

TITLE:

SEMICONDUCTOR SUBSTRATE STRUCTURE

CERTIFICATE OF FIRST CLASS MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence, and any document(s) referred to as enclosed herein, is/are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Mail Stop Amendment Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 10th day of January, 2005.

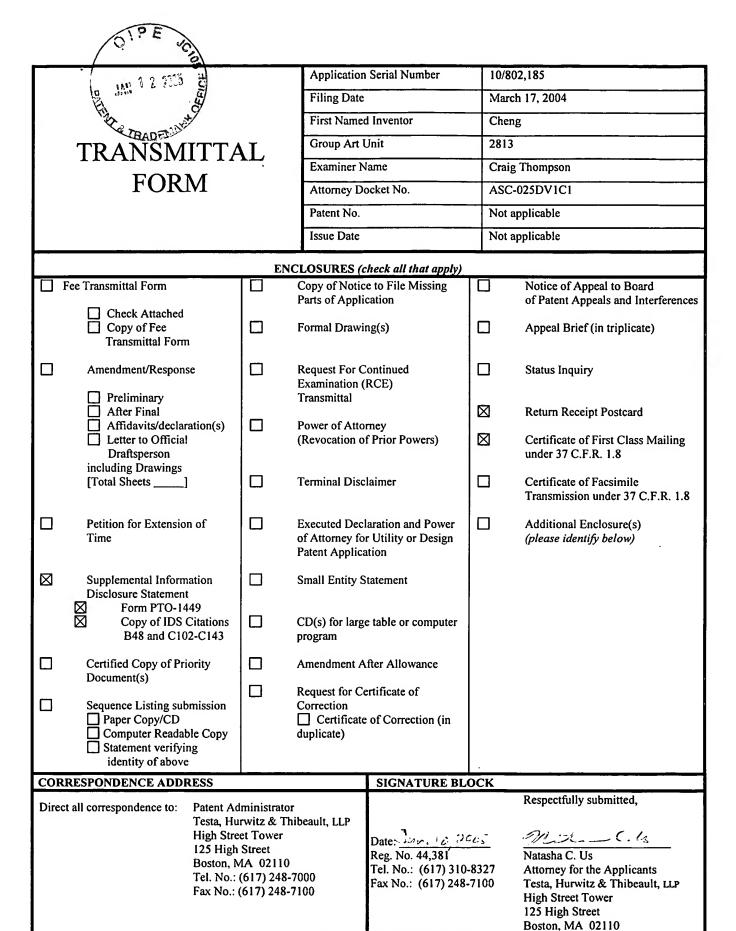
Wendy Martin

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Submitted herewith are: Transmittal Form (1 page); Supplemental Information Disclosure Statement (2 pages); Form PTO-1449 (4 pages); References labeled B48 and C102-C143; and a return receipt postcard.

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. Copies of the patents and publications are enclosed.

REMARKS

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK ONE):

(1)	within three (3) months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the date of entry of the national stage as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the first Office action on the merits, or before the mailing of a first Office action after the filing of a request for continued examination under 37 C.F.R. 1.114; or
(2)	after the period defined in (1) but before the mailing date of a final action or a notice of allowance under 37 C.F.R. 1.311, and
	the requisite Statement is below, OR
	the requisite fee under 37 C.F.R. 1.17(p), namely \$180.00, is included herein, or

Supplemental Information Disclosure Statement Serial No. 10/802,185 Page 2 after the mailing date of a final action or notice of allowance but before the payment (3) of the issue fee, AND the requisite Statement is below, AND the requisite petition fee under 37 C.F.R. 1.17(p), namely \$180.00 is included herein. It is respectfully requested that the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application. Respectfully submitted, notes (il Date: (300, 10 3005) Reg. No. 44,381 Natasha C. Us Attorney for the Applicants Testa, Hurwitz, & Thibeault, LLP Tel. No.: (617) 310-8327 High Street Tower Fax No.: (617) 248-7100 125 High Street Boston, Massachusetts 02110

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ATTORNEY DOCKET NO.: ASC-025DVC1 **FORM PTO - 1449** APPLICANTS: Cheng et al. INFORMATION DISCLOSURE STATEMENT SERIAL NO.: 10/802,185 FILING DATE: March 17, 2004 1AN 1 2 2005 2813 GROUP: BADEMA **U.S. PATENT DOCUMENTS SUB** FILING DATE IF DATE NAME CLASS DOCUMENT EXAM. **CLASS** APPROPRIATE NUMBER INIT. FOREIGN PATENT DOCUMENTS COUNTRY **ENGLISH** DOCUMENT DATE **CLASS** SUB FILING **ABSTRACT** EXAM. LANG (Y/N) CODE **CLASS** DATE **ONLY** NUMBER INIT. Υ Y 09/02/1994 JP **B48** 6-244112 OTHER ART, JOURNAL ARTICLES, ETC. OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication) EXAM. INIT. Batterman, "Hillocks, Pits, and Etch Rate in Germanium Crystals," Journal of Applied Physics, Vol. 28, No. C102 11 (November, 1957), pp. 1236-1241. Bohg, "Ethylene Diamine-Pyrocatechol-Water Mixture Shows Etching Anomaly in Boron-Doped Silicon," C103 Journal of the Electrochemical Society, Vol. 118, No. 2 (February 1971), pp. 401-402. Brunner et al., "Molecular beam epitaxy growth and thermal stability of Si_{1-x}Ge_x layers on extremely thin C104 silicon-on-insulator substrates," Thin Solid Films, Vol. 321 (1998), pp. 245-250. Chen et al., "The Band Model and the Etching Mechanism of Silicon in Aqueous KOH," Journal of the C105 Electrochemical Society, Vol. 142, No. 1 (January 1995), pp. 170-176. Desmond et al., "The Effects of Process-Induced Defects on the Chemical Selectivity of Highly Doped C106 Boron Etch Stops in Silicon," Journal of the Electrochemical Society, Vol. 141, No. 1 (January 1994), pp. 178-184. Ehman et al., "Morphology of Etch Pits on Germanium Studied by Optical and Scanning Electron C107 Microscopy," Journal of Applied Physics, Vol. 41, No. 7 (June 1970), pp. 2824-2827. Feijóo et al., "Etch Stop Barriers in Silicon Produced by Ion Implantation of Electrically Non-Active C108 Species," Journal of the Electrochemical Society, Vol. 139, No. 8 (August 1992), pp. 2309-2313. Finne et al., "A Water-Amine-Complexing Agent System for Etching Silicon," Journal of the C109 Electrochemical Society, Vol. 114, No. 9 (September 1967), pp. 965-970. Fitzgerald, "GeSi/Si Nanostructures," Annual Review of Materials Science, Vol. 25 (1995), pp. 417-454. C110 Frank, "Orientation-Dependent Dissolution of Germanium," Journal of Applied Physics, Vol. 31, No. 11 C111 (November 1960), pp.1996-1999.

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